

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of: Eldridge et al. Application No.: Unknown Filing Date: December 27, 2001 For: PROBE CARD ASSEMBLY AND KIT, AND METHODS OF USING SAME	Examiner: Unknown Group Art Unit: Unknown
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3 / Prel. Amdt.
B
E. Willis
8-26-02

PRELIMINARY AMENDMENT

Box: New Application
Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to examination of the above-identified patent application (which is filed herewith), please amend the application as follows:

In The Claims

Please cancel claim 1 without prejudice.

Please add new claims 43-57 as follows:

43. (New) A tested semiconductor device produced by a process comprising the steps of:
providing a wafer having a plurality of semiconductor devices thereon, each of said semiconductor devices including a plurality of electrical contact pads;
providing a probe card assembly, said probe assembly including a probe card having a plurality of electrical contacts, a probe substrate having a plurality of elongate, resilient probe elements, and a compliant interconnection structure electrically connecting said ones of said electrical contacts with corresponding ones of said probe elements;
contacting said wafer and said probe card assembly such that ones of said electrical contact pads of said semiconductor devices are in electrical contact with ones of said probe elements; and
testing said semiconductor devices.